

## What is Claimed is:

- [c1] A computerized method of calculating a custom die price, comprising:
- providing an interface for designating base parameters;
  - selecting a base die based on the base parameters;
  - creating a reference die based on a design methodology and the base parameters;
  - calculating a complexity factor based on designated custom parameters and the reference die; and
  - calculating the custom die price based on the base die, the custom parameters and the complexity factor.
- [c2] The method of claim 1, wherein the base parameters include a technology, an X-dimension, a Y-dimension and a number of levels of metal.
- [c3] The method of claim 1, wherein the selecting step includes:
- providing a set of possible base dies based on the designated chip parameters; and selecting the base die from the set of possible base dies.
- [c4] The method of claim 1, wherein the reference die is a most complex die available based on the designated base parameters.
- [c5] The method of claim 1, wherein the custom parameters include a core, an oxide level, a solder type, a cell logic circuit count, register array parameters and memory parameters.
- [c6] The method of claim 1, wherein the calculating a complexity factor step includes:
- creating a custom die having the base parameters and the custom parameters;
  - determining a custom die yield;
  - determining a reference die yield; and
  - dividing the custom die yield by the reference die yield to provide the complexity factor.
- [c7] The method of claim 1, wherein the calculating the custom die price step

includes:

- calculating a base die price for the base die;
- providing the custom die price by modifying the base die price based on the custom parameters; and
- adjusting the custom die price using the complexity factor.

[c8] The method of claim 1, further comprising calculating a chip price based on the custom die price and designated package parameters.

[c9] The method of claim 8, further comprising:  
designating a chip quantity; and  
adjusting the chip price based on the chip quantity.

[c10] A computerized method of calculating a custom die price, comprising:  
designating base parameters;  
calculating a base die price based on the base parameters;  
creating a reference die based on a design methodology and the base parameters;  
creating a custom die by designating custom parameters;  
calculating a complexity factor based on the custom die and the reference die; and  
calculating the custom die price based on the base die price, the custom die and the complexity factor.

[c11] The method of claim 10, wherein the designating step includes:  
providing a set of possible base dies; and  
selecting a base die from the set of possible base dies.

[c12] The method of claim 11, wherein the designating step further includes selecting a first base parameter, wherein each possible base die includes the first base parameter.

[c13] The method of claim 10, wherein the calculating a complexity factor step includes:

- determining a custom die yield based on the custom die;
- determining a reference die yield based on the reference die; and

dividing the custom die yield by the reference die yield to provide the complexity factor.

- [c14] The method of claim 10, wherein the calculating the custom die price step includes:
- modifying the base die price based on the custom parameters to provide the custom die price; and
  - adjusting the custom die price using the complexity factor.
- [c15] The method of claim 10, further comprising calculating a chip price based on the custom die price and designated package parameters.
- [c16] The method of claim 15, further comprising:
- designating a chip quantity; and
  - adjusting the chip price based on the chip quantity.
- [c17] A system for determining a custom die price, comprising:
- a base die system for designating base parameters;
  - a reference die system for creating a reference die based on the base parameters and a design methodology;
  - a custom die system for designating custom parameters;
  - a complexity system for calculating a complexity factor based on the custom parameters and the reference die; and
  - a calculation system for calculating the custom die price based on the base parameters, the custom parameters and the complexity factor.
- [c18] The system of claim 17, further comprising a packaging system for calculating a chip price based on the custom die price and designated packaging parameters.
- [c19] The system of claim 18, further comprising a volume system for adjusting the chip price based on a designated quantity.
- [c20] A computer program product comprising a computer useable medium having computer readable program code embodied therein for determining a custom die price, the program product comprising:
- program code for designating base parameters;

program code for calculating a base die price based on the base parameters;  
program code for creating a reference die based on a design methodology and the base parameters;  
program code for creating a custom die by designating custom parameters;  
program code for calculating a complexity factor based on the custom die and the reference die; and  
program code for calculating a custom die price based on the base die price, the custom die and the complexity factor.

- [c21] The computer program product of claim 20, wherein the program code for designating base parameters includes:
- program code for providing a set of possible base dies; and
  - program code for selecting a base die from the set of possible base dies.
- [c22] The computer program product of claim 21, wherein the program code for designating base parameters further includes program code for selecting a first base parameter, wherein each possible base die includes the first base parameter.
- [c23] The computer program product of claim 20, wherein the program code for calculating a complexity factor includes:
- program code for determining a custom die yield based on the custom die; and
  - program code for determining a reference die yield based on the reference die.
- [c24] The computer program product of claim 20, wherein the program code for calculating a custom die price includes:
- program code for calculating a custom die price for the custom die using the base die price and the custom die; and
  - program code for adjusting the custom die price using the complexity factor.

[c25] The computer program product of claim 20, further comprising program code for calculating a chip price based on the custom die price and designated package parameters.

[c26] The computer program product of claim 20, further comprising:  
program code for providing an interface for designating a chip quantity;  
and  
program code for adjusting the chip price based on the chip quantity.

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